



Material Content Data Sheet



Sales Product Name		BBY 53-02V H6327		Issued		27. September 2017			
MA#		MA000770624							
Package		PG-SC79-2-1		Weight*		1.68 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	non noble metal	arsenic	7440-38-2	0.000	0.00		18		
	noble metal	gold	7440-57-5	0.003	0.18		1787		
	inorganic material	silicon	7440-21-3	0.026	1.53	1.71	15263	17068	
leadframe	inorganic material	silicon	7440-21-3	0.000	0.01		92		
	non noble metal	titanium	7440-32-6	0.001	0.05		460		
	non noble metal	chromium	7440-47-3	0.002	0.14		1379		
	non noble metal	copper	7440-50-8	0.767	45.78	45.98	457907	459838	
wire	non noble metal	copper	7440-50-8	0.007	0.41	0.41	4058	4058	
encapsulation	organic material	carbon black	1333-86-4	0.007	0.43		4338		
	plastics	epoxy resin	-	0.124	7.37		73742		
	inorganic material	silicondioxide	60676-86-0	0.596	35.57	43.37	355698	433778	
leadfinish	non noble metal	tin	7440-31-5	0.055	3.26	3.26	32572	32572	
plating	noble metal	silver	7440-22-4	0.088	5.27	5.27	52686	52686	
*deviation	< 10%				Sum in total:		100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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